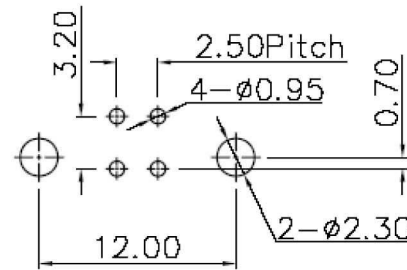
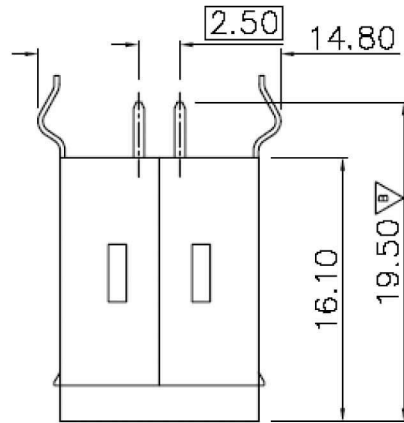
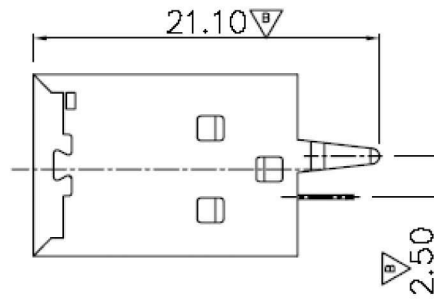
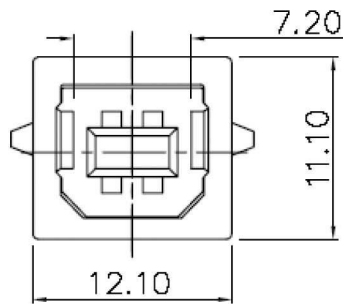


△					
MARK	SIGN	DAET	ECN NO.	REVISIONS	REV. APPROVED



RECOMMEND PCB LAYOUT(±0.05)



NOTES:

- MATERIAL:
  - HOUSING: HIGH-THERMOPLASTIC, UL94V-0, BLACK Or WHITE
  - TERMIANL: COPPY ALLOY
  - SHELL: STAINLESS STEEL
- FINISHING
  - TERMINAL: GOLD FLASH PLATING ON SOLDER TAILS.
  - SHELL: 50μ" MIN. NICKEL UNDER, 50μ" MATTE TIN OVER ALL.
- ELECTRICAL CHARACTERISTICS:
  - CURRENT RATING: 1AMP. MAX. PER CONTACT
  - LOW LEVEL CONTACT RESISTANCE: 50MILLIOHMS
  - DIELECTRIC WITHSTANDING VOLTAGE: 500V AC MIN. FOR 1 MINUTE, WITH 1mA MAX. CURRENT LEAKAGE.
  - INSULATION RESISTANCE: 100 MEGAOHMS MIN. INITIAL AT 100VDC.
- MECHANICAL CHARACTERISTICS:
  - MATING FORCE: 40N(4.0kgf) MAX.
  - UNMATING FORCE: 10N(1.02kgf) MIN.
  - CONTACT RETENTION FORCE: 1.47N(0.15kgf) MIN.
  - DURABILITY: 5000 TIMES MATING/UNMATING CYCLES.
- ENVIRONMENTAL CHARACTERISTICS:
  - OPERATING TEMPERATURE: -0°C TO +50°C.
  - STORAGE TEMPERATURE: -20°C TO +60°C.
  - SALT SPRAY: SALT WATER DENSITY OF 5%, TEMPERATURE OF 35°C, TIME 24HOUR.

# SUGO INDUSTRIAL CO., LTD

UNLESS OTHERWISE SPECIFIED TOLERANCE							
ANG	TOL	DIM	TOL(1)	TOL(2)	TOL(3)	TOL(4)	TOL(5)
0~5	±0.1	0~1	±0.015	±0.02	±0.03	±0.05	±0.10
10~20	±0.2	1~3	±0.02	±0.03	±0.05	±0.08	±0.13
20~40	±0.3	3~6	±0.03	±0.05	±0.08	±0.10	±0.15
40~60	±0.5	6~12	±0.05	±0.08	±0.10	±0.13	±0.18
60~90	±0.8	12~18	±0.08	±0.10	±0.13	±0.15	±0.20
90~120	±1.0	18~34	±0.10	±0.13	±0.15	±0.18	±0.25
120~150	±1.5	34~50	±0.13	±0.15	±0.18	±0.20	±0.30
150~180	±1.8	50~100	±0.15	±0.18	±0.20	±0.25	±0.35

	DRAWN	H.Q.huocy	TITLE 2.0 USB / B Type Top Entry / DIP Type	
	UNIT	MM	PART NO. <b>USB-B-04TE-DP</b>	
SCALE	1:1	APPROVED	DATE 2007. 05. 28	REV. A/0